

Amendments to the Abstract:

Please replace the Abstract with the following amended Abstract:

An electronic package substrate for an electronic package that includes an adhesive bonding member having two planar surfaces and an orifice there through for receiving a chip and a circuitized member having two planar surfaces, one surface being bonded to one of the planar surfaces of the bonding member, ~~said the~~ circuitized member being electrically connectable to the chip. The electronic package substrate is fabricated for an electronic package for either a wire bonded chip, a tab bonded chip, or a flip chip. ~~An electronic package for a wire bonded chip or tab bonded chip that includes an adhesive bonding member having two planar surfaces and an orifice there through; a circuitized member bonded to one of the planar surfaces and having an orifice there through overlying the orifice in the bonding member; a support member bonded to the other planar surface, blocking the orifices, thereby forming a cavity; and a chip bonded within the cavity to the support member and electrically connected to the circuitized member. An electronic package substrate for an electronic package for a flip chip includes an adhesive bonding member having two planar surfaces and an orifice there through, a circuitized member bonded to one of the planar surfaces and blocking the orifice, thereby forming a cavity for receiving a flip chip, and an array of solder pads on the circuitized member within the cavity. A process for fabricating an electronic package substrate including the steps of fabricating an adhesive bonding member and a circuitized member, aligning the members with respect to each other, sandwiching the members together, and bonding the members together with heat and pressure.~~